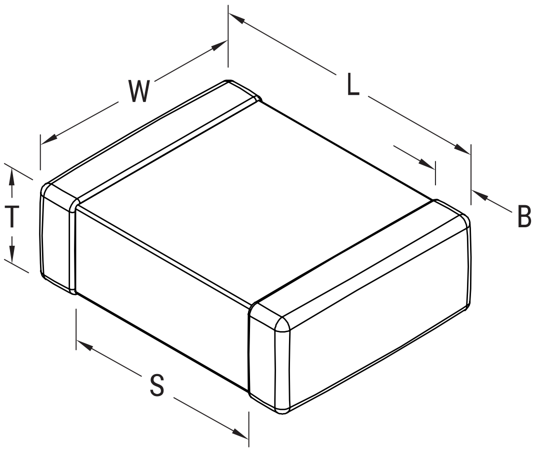
C1206X333M3GEC

ESD SMD Comm C0G, Ceramic, 0.033 uF, 20%, 25 VDC, C0G, SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I, 1206, 1.5 mm



Click here for the 3D model.

General Information

Series	ESD SMD Comm C0G
Style	SMD Chip
Description	SMD, MLCC, Temperature Stable, Electro Static Discharge, Class I
Features	Temperature Stable, Low ESR, Class I
RoHS	Yes
Termination	Flexible Termination
Marking	No
AEC-Q200	No
Typical Component Weight	30 mg
Shelf Life	78 Weeks
MSL	1

Dimensions

Chip Size	1206
L	3.3mm +/-0.4mm
W	1.6mm +/-0.35mm
T	1.2mm +/-0.15mm
S	1.5mm MIN
B	0.6mm +/-0.25mm

Packaging Specifications

Packaging	Bulk, Bag
Packaging Quantity	1

Specifications

Capacitance	0.033 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	25 VDC
ESD Level per AEC-Q200	25,000 V ESD Level
Dielectric Withstanding Voltage	62.5 VDC
Temperature Range	-55/+125°C
Temp. Coefficient	C0G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour
Insulation Resistance	30.303 GOhms

Generated 06/29/2025